

### **DESCRIPTION**

The IS354 and IS354A optically coupled isolators each consists of two infrared light emitting diodes in reverse parallel connection allowing AC input voltage and optically coupled to an NPN silicon photo transistor in a space efficient Mini Flat Package.

#### **FEATURES**

- AC Isolation Voltage 3750V<sub>RMS</sub>
- Wide Operating Temperature Range -55°C to +100°C
- Lead Free and RoHS Compliant
- UL File E91231 Package Code "FPA1"

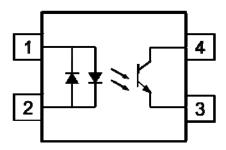
#### **APPLICATIONS**

- Computer Terminals
- Industrial System Controllers
- Measuring Instruments
- System Appliances

### **ORDER INFORMATION**

Available in Tape and Reel





### ABSOLUTE MAXIMUM RATINGS $(T_A = 25^{\circ}C)$

Exposure to absolute maximum ratings for long periods of time can adversely affect reliability.

#### Input

Forward Current	±50mA
Power dissipation	70mW

#### Output

Collector to Emitter Voltage BV <sub>CEO</sub>	35V
Emitter to Collector Voltage BV <sub>ECO</sub>	6V
Collector Current	50mA
Power Dissipation	150mW

### **Total Package**

(10s)

Isolation Voltage	$3750V_{RMS}$
Total Power Dissipation	170mW
Operating Temperature	-55 to 100 °C
Storage Temperature	-55 to 150 °C
Lead Soldering Temperature	260°C

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### **ELECTRICAL CHARACTERISTICS** (Ambient Temperature = 25°C unless otherwise specified)

### **INPUT**

Parameter	Symbol	Test Condition	Min	Тур.	Max	Unit
Forward Voltage	$V_{\mathrm{F}}$	$I_F = \pm 20 \text{mA}$		1.2	1.4	V
Terminal Capacitance	$C_{t}$	V = 0V, $f = 1KHz$		30	250	pF

### **OUTPUT**

Parameter	Symbol	Test Condition	Min	Тур.	Max	Unit
Collector - Emitter Breakdown Voltage	$BV_{CEO}$	$I_{C} = 0.1 \text{mA}, I_{F} = 0 \text{mA}$	35			V
Emitter - Collector Breakdown Voltage	BV <sub>ECO</sub>	$I_E = 10 \mu A, I_F = 0 mA$	6			V
Collector - Emitter Dark Current	$I_{CEO}$	$V_{CE} = 20V$ , $I_F = 0mA$			100	nA

### **COUPLED**

Parameter	Symbol	Test Condition	Min	Тур.	Max	Unit
Current Transfer Ratio	CTR	$I_F = \pm 1 \text{mA}, V_{CE} = 5 \text{V}$	20		400	%
		Optional CTR Grades A	50		150	
Collector - Emitter Saturation Voltage	V <sub>CE(sat)</sub>	$I_F = \pm 20 \text{mA}, I_C = 1 \text{mA}$			0.2	V
Input to Output Isolation Voltage	V <sub>ISO</sub>	R.H. = 40% - 60%, 1 minute Note 1	3750			$V_{RMS}$
Input to Output Isolation Resistance	R <sub>ISO</sub>	V <sub>IO</sub> = 500V, R.H. = 40% to 60% Note 1	5x10 <sup>10</sup>			Ω
Floating Capacitance	$C_{\mathrm{f}}$	V = 0V, $f = 1MHz$		0.6	1	pF
Output Rise Time	$t_{\rm r}$	W 2V I 2 A B 1000		4	18	μs
Output Fall Time	$t_{\mathrm{f}}$	$V_{CE} = 2V$ , $Ic = 2mA$ , $R_L = 100\Omega$		3	18	μs

Note 1: Measure with input leads shorted together and output leads shorted together.



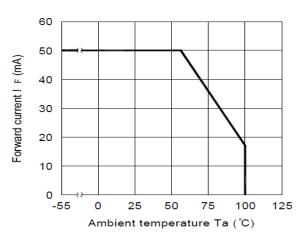


Fig 1 Forward Current vs T<sub>A</sub>

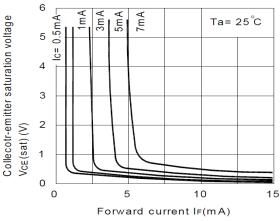


Fig 3 Collector-emitter Saturation Voltage vs Forward Current

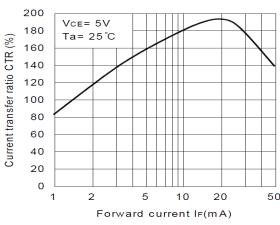


Fig 5 Current Transfer Ratio vs Forward Current

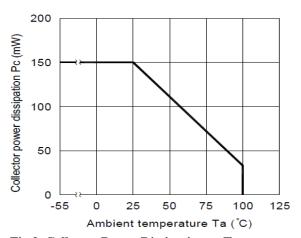


Fig 2 Collector Power Dissipation vs T<sub>A</sub>

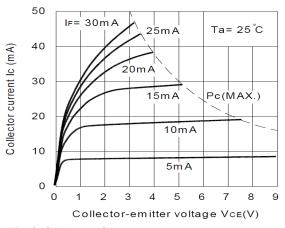


Fig 4 Collector Current vs Collector-emitter Voltage

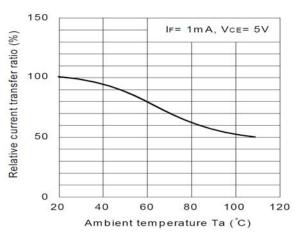


Fig 6 Relative Current Transfer Ratio vs T<sub>A</sub>



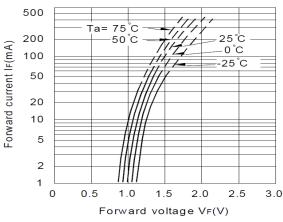


Fig 7 Forward Current vs Forward Voltage

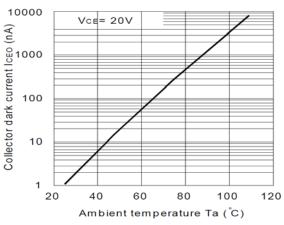


Fig 9 Collector Dark Current vs T<sub>A</sub>

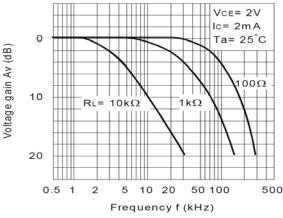


Fig 11 Frequency Response

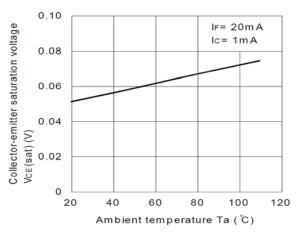


Fig 8 Collector-emitter Saturation Voltage vs T<sub>A</sub>

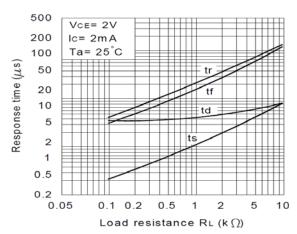
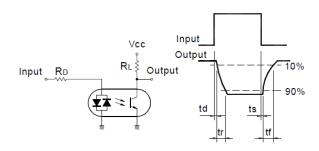


Fig 10 Response Time vs Load Resistance



**Response Time Test Circuit** 



### **ORDER INFORMATION**

IS354, IS354A			
After PN	PN	Description	Packing quantity
None	IS354, IS354A	Surface Mount Tape & Reel	3000 pcs per reel

### **DEVICE MARKING**



FPA1 denotes Device Part Number

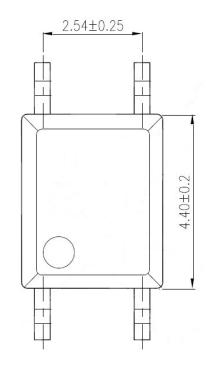
I denotes Isocom

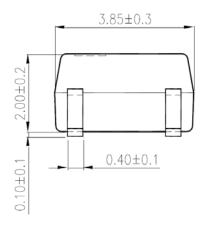
Y denotes 1 digit Year code WW denotes 2 digit Week code

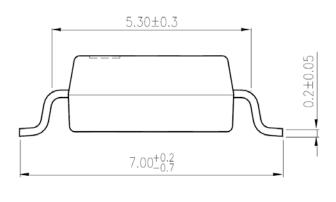
R denotes CTR Grade



## PACKAGE DIMENSIONS (mm)

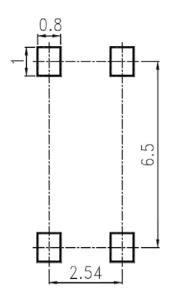




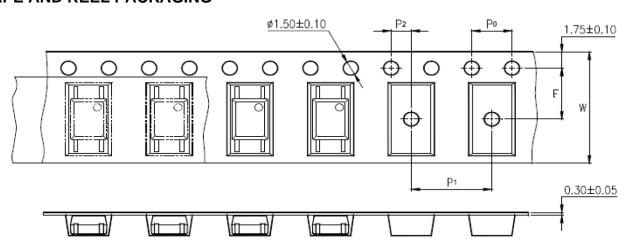




## **RECOMMENDED SOLDER PAD LAYOUT (mm)**



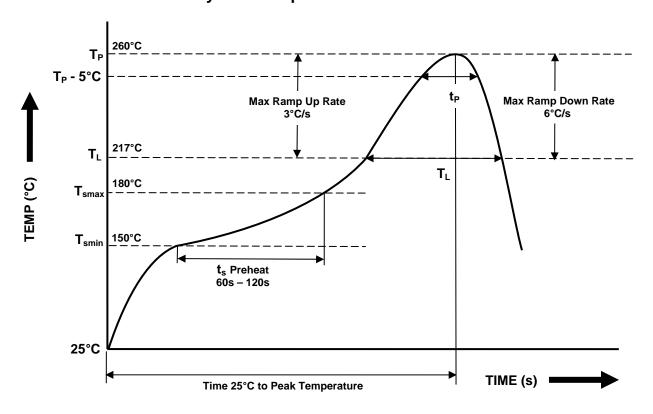
### **TAPE AND REEL PACKAGING**



Description	Symbol	Dimension mm (inch)
Tape Width	W	12 ± 0.3 (0.47)
Pitch of Sprocket Holes	P <sub>0</sub>	4 ± 0.1 (0.15)
Dictance of Compartment to Spreaket Heles	F	5.5 ± 0.1 (0.217)
Distance of Compartment to Sprocket Holes	P <sub>2</sub>	2 ± 0.1 (0.079)
Distance of Compartment to Compartment	P <sub>1</sub>	8 ± 0.1 (0.315)



### IR REFLOW SOLDERING TEMPERATURE PROFILE One Time Reflow Soldering is Recommended. Do not immerse device body in solder paste.



Profile Details	Conditions
$ \begin{array}{l} \textbf{Preheat} \\ \textbf{- Min Temperature } (T_{SMIN}) \\ \textbf{- Max Temperature } (T_{SMAX}) \\ \textbf{- Time } T_{SMIN} \text{ to } T_{SMAX} \left(t_s\right) \end{array} $	150°C 180°C 60s - 120s
	260°C 217°C 20s 60s 3°C/s max 3 - 6°C/s
Average Ramp Up Rate (T <sub>smax</sub> to T <sub>P</sub> )	3°C/s max
Time 25°C to Peak Temperature	8 minutes max



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